

# Product / Process Change Notification



N° 2018-013-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Capacity Extension by Introduction of 300mm Wafer Diameter for Dedicated OptiMOS™ Products at Infineon Technologies Dresden, Germany & Harmonization of Bill of Material (BoM)

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **27<sup>th</sup> July 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Eckart Süner  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

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► **Products affected:**

Please refer to attached affected product list 1\_cip18013\_a.xlsx

► **Detailed Change Information:**

**Subject:** (a) Introduction of 300mm wafer diameter at Infineon Technologies Dresden GmbH.  
 (b) Standardization of pad design and metallization process  
 (c) Standardization of mould compound for TDSON-8 package  
 (d) Standardization of gate wire bond for TDSON-8 package

**Reason:** (a) Next phase of Front End capacity expansion by introduction of 300mm wafer diameter to support continuous increasing customer demand.  
 (b), (c), (d) Standardization of bill of material (BoM) allows Infineon to improve efficiency & flexibility in the manufacturing environment by significant complexity reduction within the whole production chain.

**Description:**

	<u>Old</u>	<u>New</u>
(a) Wafer production sites with wafer diameter:	<ul style="list-style-type: none"> <li>■ Infineon Technologies Austria AG, Villach, Austria (200mm)</li> </ul>	<ul style="list-style-type: none"> <li>■ Infineon Technologies Austria AG, Villach, Austria (200mm)</li> <li style="text-align: center;"><i>and</i></li> <li>■ Infineon Technologies Dresden GmbH, Germany (300mm)</li> </ul>
(b) Standardization of pad design and metallization process:	<ul style="list-style-type: none"> <li>■ Al/Cu</li> <li style="text-align: center;"><i>and</i></li> <li>■ Cu</li> </ul>	<ul style="list-style-type: none"> <li>■ Cu</li> </ul>
(c) Standardizing mould compound TDSON-8 package:	<ul style="list-style-type: none"> <li>■ Hitachi CEL 1772</li> </ul>	<ul style="list-style-type: none"> <li>■ Hitachi CEL 9240</li> </ul>
(d) Standardizing of gate wire bond TDSON-8 package:	<ul style="list-style-type: none"> <li>■ 38µm Au</li> <li style="text-align: center;"><i>and</i></li> <li>■ 30µm Au</li> </ul>	<ul style="list-style-type: none"> <li>■ 30µm Au</li> </ul>

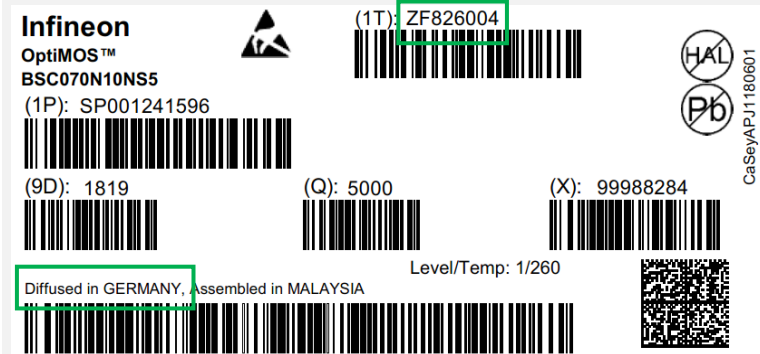
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## ► Product Identification:

External traceability: assured via Waferlot number & country of diffusion



## ► Impact of Change:

**NO** change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

**NO** change in existing datasheet parameters

**NO** change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.

## ► Attachments:

Affected product list 1\_cip18013\_a.xlsx

Qualification Report 2\_cip18013\_a.pdf

## ► Time Schedule:

- |                               |  |
|-------------------------------|--|
| ■ Final qualification report: | available                                    |
| ■ First samples available:    | on request                                   |
| ■ Intended start of delivery: | 01-09-2018 or earlier upon customer approval |

## Summary:

**All changes to be applied reflect Infineon's efforts to respond to increasing customer demand in mid and long term.**

If you have any questions, please do not hesitate to contact your local Sales office.